

WHAT IS CLAIMED IS:

1 1. A system of manufacturing a liquid crystal display, the system comprising:
2 a panel manufacturing unit for manufacturing a liquid crystal panel assembly including a
3 thin film transistor (TFT) array panel, a color filter array panel, and a liquid crystal layer
4 interposed between the TFT array panel and the color filter array panel;
5 a printed circuit film bonding unit for bonding a printed circuit film on the panel
6 assembly;
7 a printed circuit board (PCB) bonding unit for bonding a PCB to the printed circuit film;
8 and
9 an inspection unit for inspecting the bonding of the printed circuit film on the panel
10 assembly.

1 2. The system of claim 1, wherein the printed circuit film comprises a tape carrier
2 package.

1 3. The system of claim 1, wherein the inspection unit comprises a differential
2 camera or a differential scope.

1 4. The system of claim 1, wherein the printed circuit film bonding unit bonds the
2 printed circuit film on the panel assembly with an anisotropic conductive film (ACF).

1 5. The system of claim 4, wherein the ACF comprises an adhesive containing a
2 plurality of conductive particles.

1 6. The system of claim 5, wherein the printed circuit film bonding unit bonds the
2 printed circuit film on the panel assembly by compression.

1 7. The system of claim 6, wherein the inspection unit detects dents generated by the
2 compression.

1 8. The system of claim 1, wherein the inspection unit detects alignment of the
2 printed circuit film with the panel assembly.

1 9. The system of claim 1, wherein the bonding inspection unit is incorporated into
2 the printed circuit film bonding unit or the PCB bonding unit.

1 10. The system of claim 1, wherein the bonding inspection unit comprises two sub-
2 units for inspection before and after the bonding of the PCB, respectively.

1 11. The system of claim 10, wherein one of the sub-units of the bonding inspection
2 unit is incorporated into the printed circuit film bonding unit and the other of the sub-units of the
3 bonding inspection unit is incorporated into the PCB bonding unit.

1 12. A method of manufacturing a liquid crystal display, the method comprising:
2 manufacturing a liquid crystal panel assembly;
3 bonding a printed circuit film on the panel assembly;
4 inspecting the bonding of the printed circuit film on the panel assembly; and
5 bonding a printed circuit board (PCB) to the printed circuit film.

1 13. The method of claim 12, wherein the inspection is performed before the bonding
2 of the PCB.

1 14. The method of claim 13, further comprising:
2 inspecting the bonding of the printed circuit film on the panel assembly again after the
3 bonding of the PCB.

1 15. The method of claim 12, wherein the inspection is performed after the bonding of
2 the PCB.

1 16. The method of claim 12, wherein the printed circuit film comprises a tape carrier
2 package.

1 17. The method of claim 12, wherein the inspection is performed using a differential
2 camera or a differential scope.

1 18. The method of claim 12, wherein the printed circuit film is bonded on the panel
2 assembly with an anisotropic conductive film (ACF) containing a plurality of conductive
3 particles.

1 19. The method of claim 18, wherein the bonding of the printed circuit film is
2 performed by thermocompression.

1 20. The method of claim 19, wherein the inspection detects dents generated by the
2 thermocompression.